



Power line chokes

Current-compensated ring core triple chokes

800 μ H, 520/300 V AC, 50 A, +60 °C

Ordering code: B82748S4503A020

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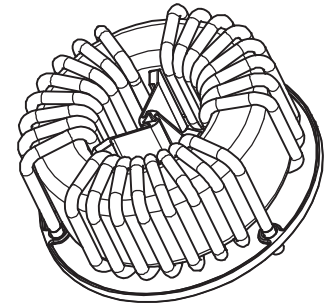
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Rated voltage 520/300 V AC

Rated current 50 A / +60 °C

Rated inductance 800 μ H



Construction

- Current-compensated ring core triple choke
- Ferrite core with epoxy coating (UL 94 V-0)
- Additional core insulation (CTI \geq 250 V)
- Polyamid spacer (UL 94 V-0, CTI \geq 550 V)
- Polycarbonate base plate (UL 94 V-0)
- Sector winding
- Clearance distances \geq 5.3 mm

Features

- High resonance frequency
- Approx. 1.0% stray inductance for differential-mode interference suppression
- Suitable for wave soldering
- Design complies with EN 60938-2 (VDE 0565-2)
- UL 1446 class 155(F) electrical insulation system
- RoHS compatible


Applications

- Suppression of common-mode interferences
- Switch-mode power applications
- Frequency converters

Terminals

- Ends of winding wires
- Hot dip tinned

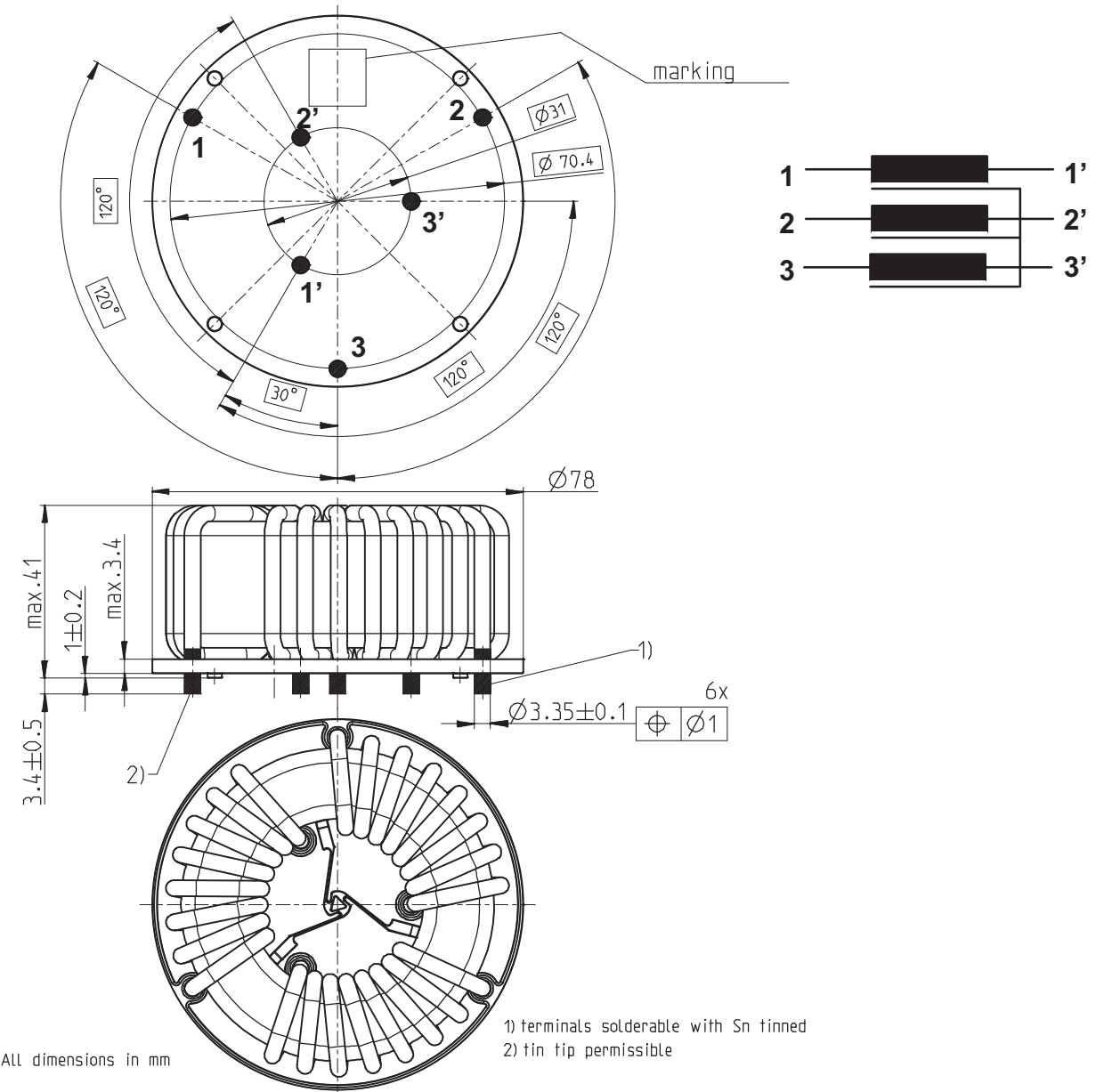
Marking

- Manufacturer, electrical insulation system designation , ordering code, rated voltages, rated inductance, rated current, date of manufacture (YYWWD.internal ID code), factory identification code

Delivery mode

- cardboard box

Dimensional drawing and pin configuration

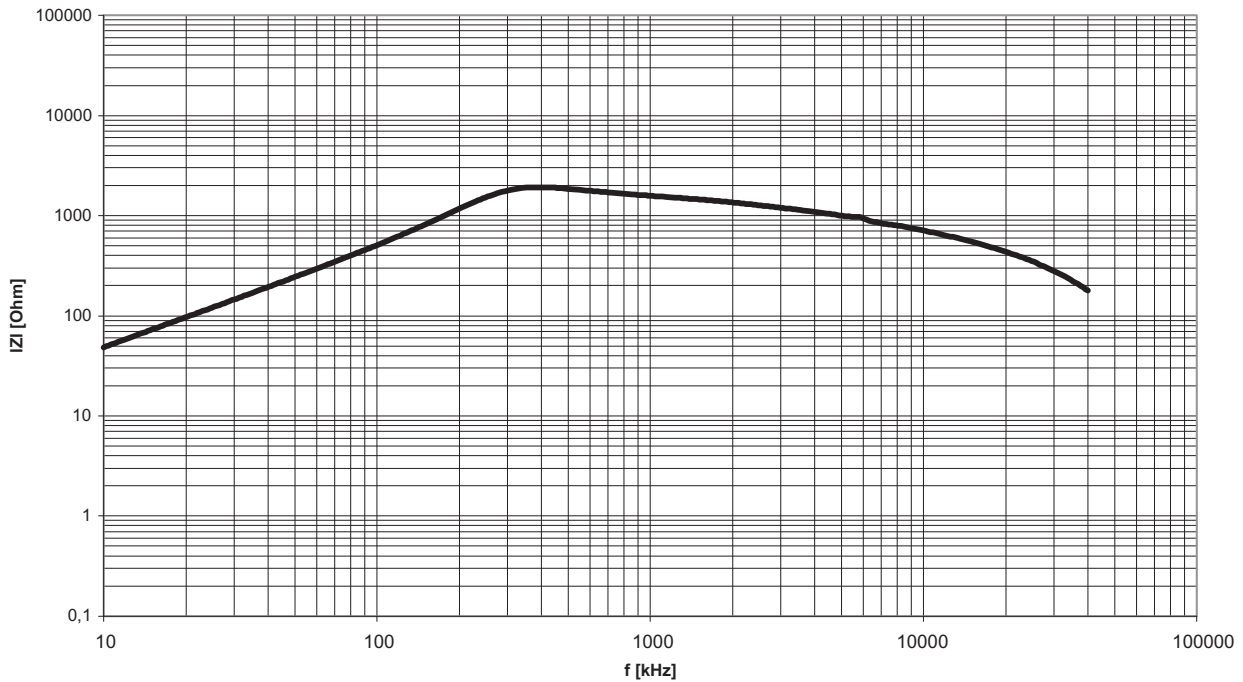


Tolerances to ISO 2768-c unless otherwise noted

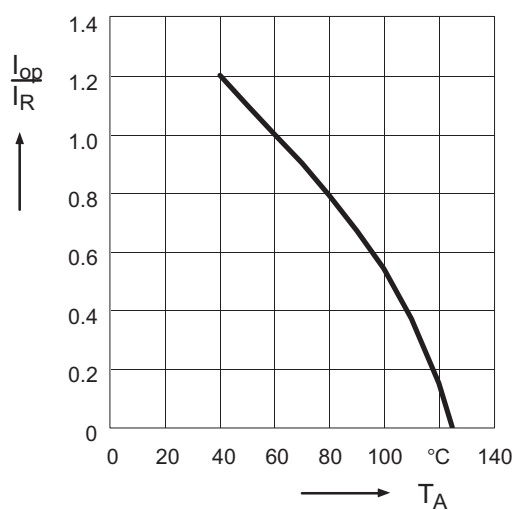
Technical data and measuring conditions

Rated voltage V_R	520/300 V AC / (50/60 Hz)
Test voltage V_{test}	2800 V AC, 2 s (line/line)
Rated temperature T_R	+60 °C
Rated current I_R	50 A Referred to rated temperature
Rated inductance L_R	800 μ H Measured with Agilent 4284A at 100 kHz, 0.1 mA, +20 °C Inductance is specified per winding.
Inductance tolerance	-30/+50% at +20 °C
Inductance decrease $\Delta L/L_0$	< 10% at DC magnetic bias with I_R , +20 °C
Stray inductance $L_{stray,typ}$	7.5 μ H Measured with Agilent 4284A at 100 kHz, 5 mA, +20 °C, typical value
DC resistance R_{typ}	1.5 m Ω Measured at +20 °C, typical value, specified per winding
Solderability (lead-free)	Sn96.5Ag3.0Cu0.5: +(245 \pm 5) °C, (3 \pm 0.3) s Wetting of soldering area \geq 95% (to IEC 60068-2-20, test Ta)
Resistance to soldering heat (wave soldering)	+(260 \pm 5) °C, (10 \pm 1) s (to IEC 60068-2-20, test Tb)
Climatic category	40/125/56 (to IEC 60068-1)
Storage conditions (packaged)	-25 °C ... +40 °C, \leq 75% RH
Weight	Approx. 430 g

Impedance $|Z|$ versus frequency f
 measured with windings in parallel at +20 °C, typical values



Current derating I_{op}/I_R versus temperature T_A
 rated temperature = +60 °C



Cautions and warnings

Current-compensated ring core double chokes

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there. Derating must be applied in case the ambient temperature in the application exceeds the rated temperature of the component.
 - Ensure the operation temperature (which is the sum of the ambient temperature and the temperature rise caused by losses / self-heating) of the component in the application does not exceed the maximum value specified in the climatic category.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.

Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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